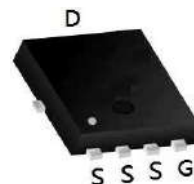


P-Ch 20V Fast Switching MOSFETs

Features:

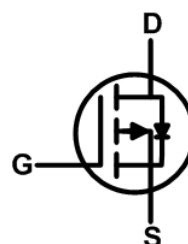
- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



PRPAK3x3 Pin Configuration

Description:

The KSPRB2627 is the high cell density trench P-ch MOSFETs, which provide excellent $R_{DS(on)}$ and gate charge for most of the synchronous buck converter applications. The KSPRB2627 meet the RoHS and Green Product requirement with full function reliability approved.



Product Summary

BVDSS	$R_{DS(on)}$	I_D
-20V	9m Ω	-48A

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 8	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, V_{GS} @ -4.5V ¹	-48	A
$I_D@T_C=70^\circ C$	Continuous Drain Current, V_{GS} @ -4.5V ¹	-38	A
I_{DM}	Pulsed Drain Current ²	-100	A
$P_D@T_C=25^\circ C$	Total Power Dissipation ³	29	W
$P_D@T_C=70^\circ C$	Total Power Dissipation ³	19	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	75	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ (t $\leq$ 10s)	40	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	4.2	$^\circ C/W$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-20	---	---	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =-1mA	---	-0.012	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-4.5V, I _D =-10A	---	---	9	mΩ
		V _{GS} =-2.5V, I _D =-8A	---	---	11.5	
		V _{GS} =-1.8V, I _D =-6A	---	---	15	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-0.3	---	-1.0	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	2.94	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-20V, V _{GS} =0V, T _J =25°C	---	---	1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±8V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =-5V, I _D =-10A	---	43	---	S
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-15V, V _{GS} =-4.5V, I _D =-10A	---	63	---	nC
Q _{gs}	Gate-Source Charge		---	9.1	---	
Q _{gd}	Gate-Drain Charge		---	13	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-10V, V _{GS} =-4.5V, R _G =3.3Ω, I _D =-10A	---	15.8	---	ns
T _r	Rise Time		---	76.8	---	
T _{d(off)}	Turn-Off Delay Time		---	193	---	
T _f	Fall Time		---	186.4	---	
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	---	5783	---	pF
C _{oss}	Output Capacitance		---	509	---	
C _{rss}	Reverse Transfer Capacitance		---	431	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,4}	V _G =V _D =0V, Force Current	---	---	-10.7	A
I _{SM}	Pulsed Source Current ^{2,4}		---	---	-60	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =-1A, T _J =25°C	---	---	-1.2	V
t _{rr}	Reverse Recovery Time	I _F =-10A, dI/dt=100A/μs, T _J =25°C	---	27	---	nS
Q _{rr}	Reverse Recovery Charge		---	17.8	---	nC

Note :

1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.

2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%

3.The power dissipation is limited by 150°C junction temperature

4.The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

Typical Characteristics

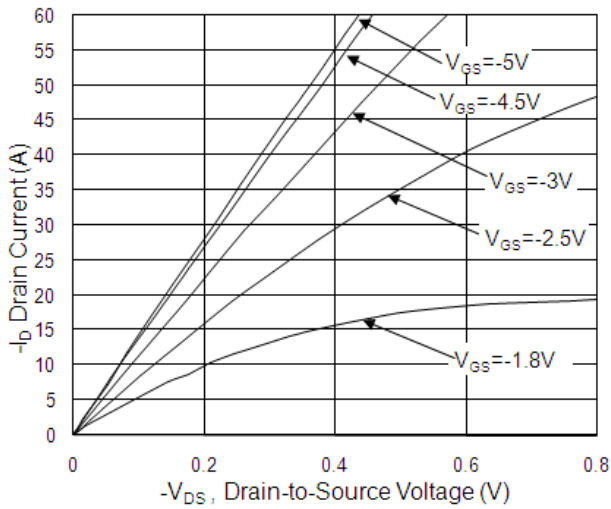


Fig.1 Typical Output Characteristics

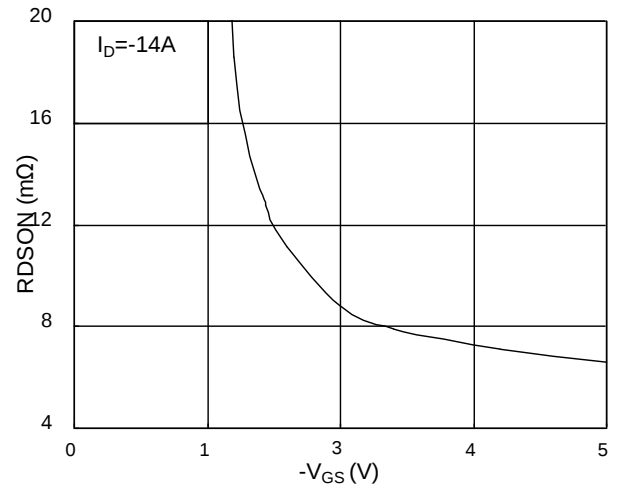


Fig.2 On-Resistance vs. G-S Voltage

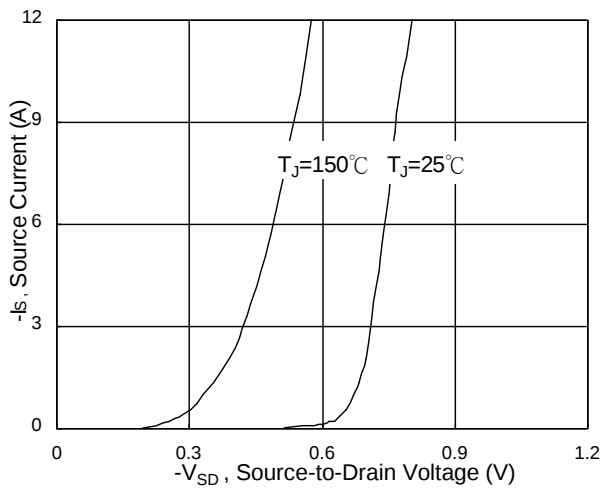


Fig.3 Forward Characteristics of Reverse

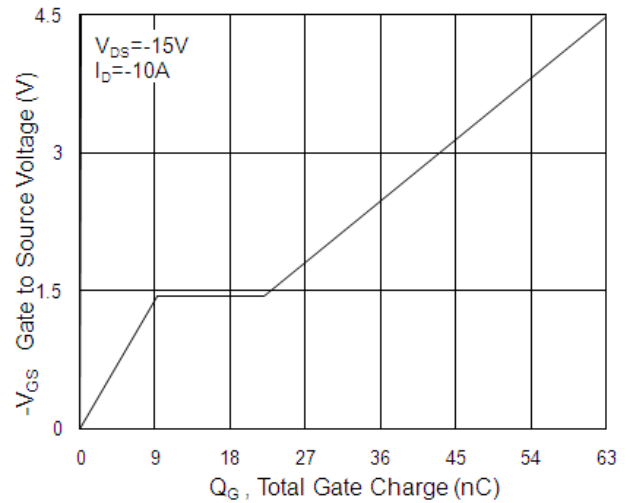


Fig.4 Gate-charge Characteristics

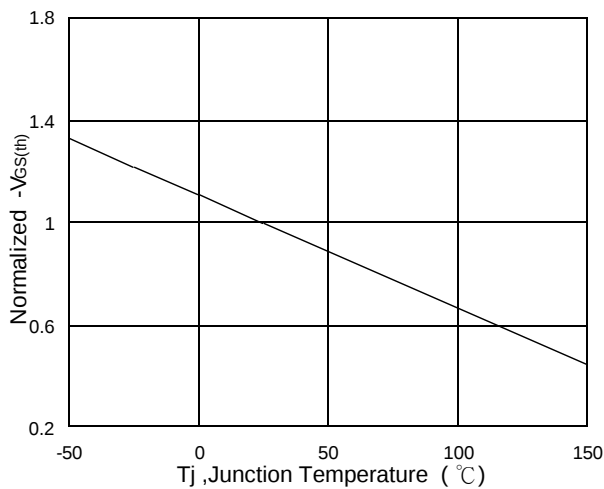


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

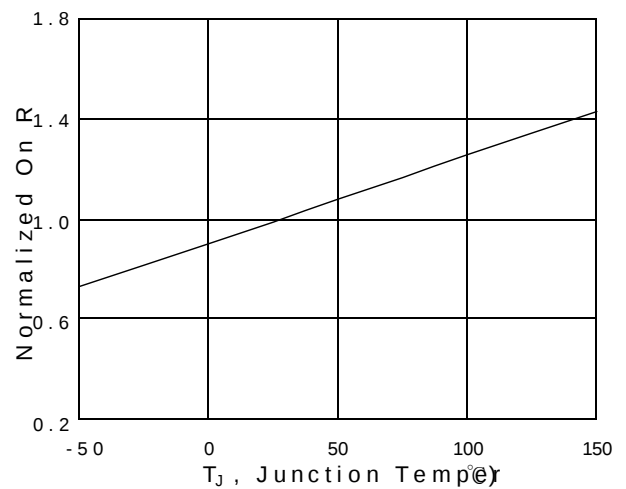


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

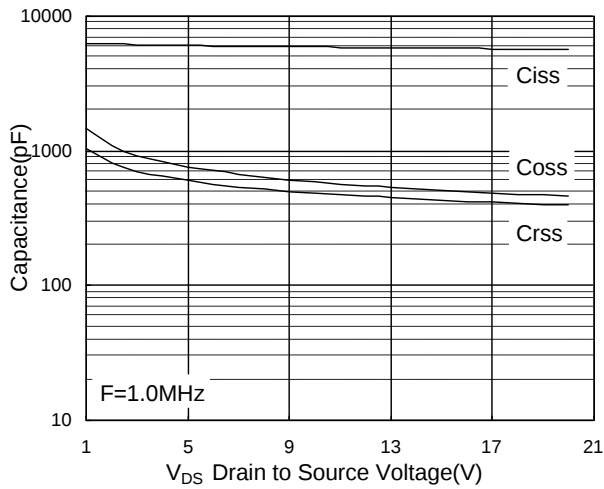


Fig.7 Capacitance

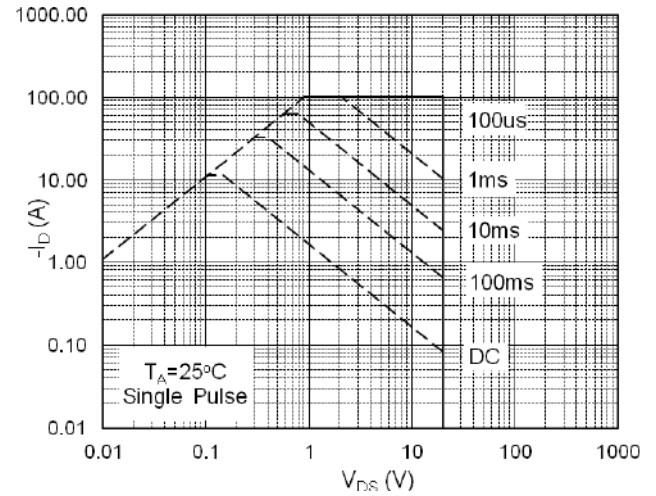


Fig.8 Safe Operating Area

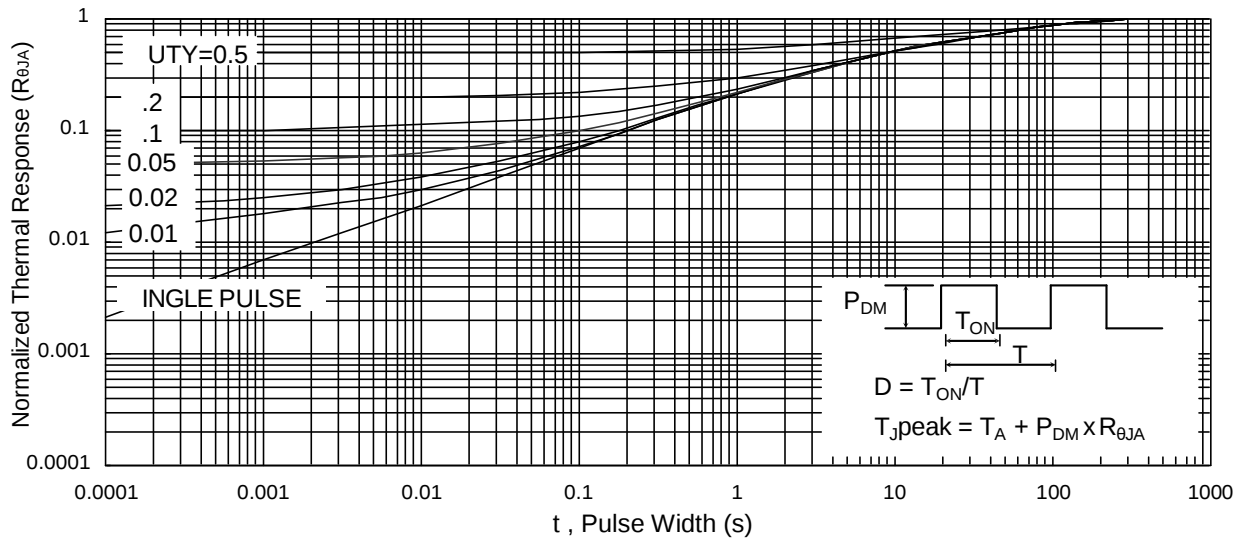


Fig.9 Normalized Maximum Transient Thermal Impedance

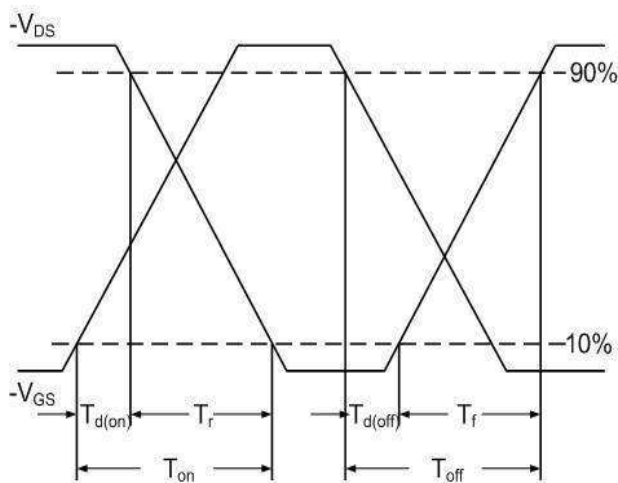


Fig.10 Switching Time Waveform

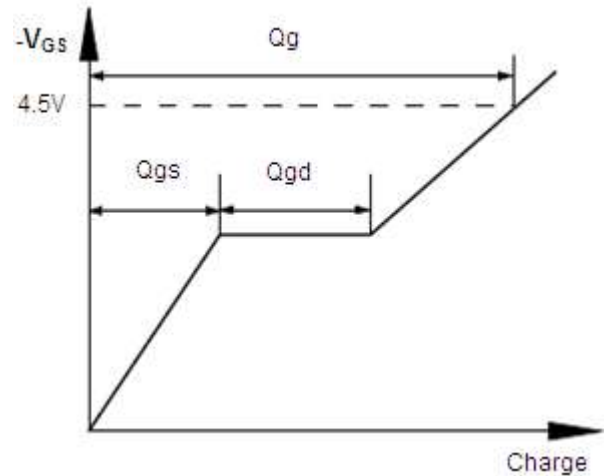


Fig.11 Gate Charge Waveform